

DATA SHEET

BF904A; BF904AR; BF904AWR N-channel dual gate MOS-FETs

Product specification
Supersedes data of 1999 Feb 01

1999 May 14

N-channel dual gate MOS-FETs

BF904A; BF904AR; BF904AWR

FEATURES

- Specially designed for use at 5 V supply voltage
- Short channel transistor with high transfer admittance to input capacitance ratio
- Low noise gain controlled amplifier up to 1 GHz
- Superior cross-modulation performance during AGC.

APPLICATIONS

- VHF and UHF applications with 3 to 7 V supply voltage such as television tuners and professional communications equipment.

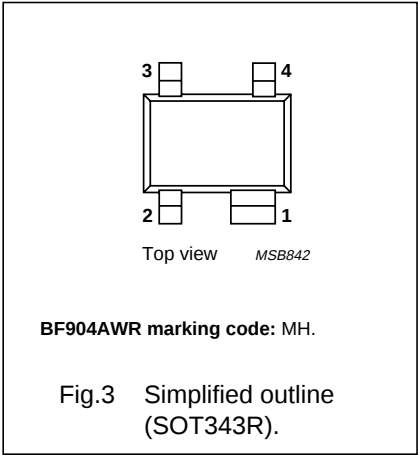
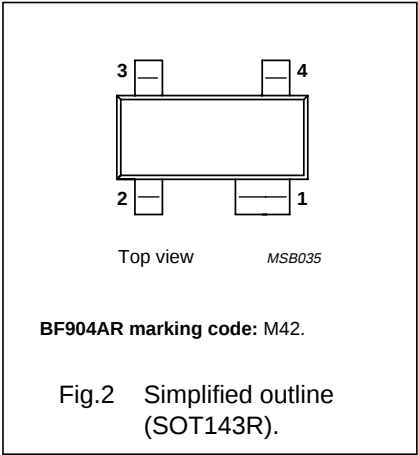
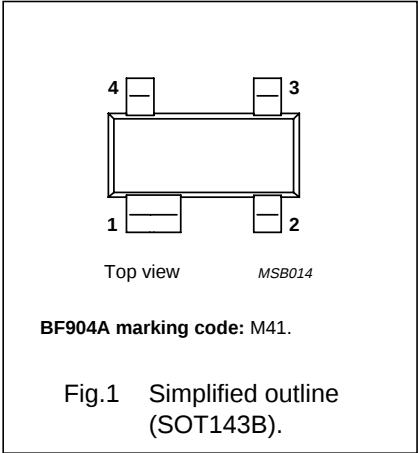
DESCRIPTION

Enhancement type field-effect transistors. The transistors consist of an amplifier MOS-FET with source and substrate interconnected and an internal bias circuit to ensure good cross-modulation performance during AGC.

The BF904A, BF904AR and BF904AWR are encapsulated in the SOT143B, SOT143R and SOT343R plastic packages respectively.

PINNING

PIN	DESCRIPTION
1	source
2	drain
3	gate 2
4	gate 1



QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{DS}	drain-source voltage		–	–	7	V
I_D	drain current		–	–	30	mA
P_{tot}	total power dissipation	$T_s \leq 110\text{ }^{\circ}\text{C}$	–	–	200	mW
$ y_{fs} $	forward transfer admittance		22	25	30	mS
C_{ig1-ss}	input capacitance at gate 1		–	2.2	2.6	pF
C_{rss}	reverse transfer capacitance	$f = 1\text{ MHz}$	–	25	35	fF
F	noise figure	$f = 800\text{ MHz}$	–	2	–	dB
T_j	operating junction temperature		–	–	150	$^{\circ}\text{C}$

CAUTION

This product is supplied in anti-static packing to prevent damage caused by electrostatic discharge during transport and handling. For further information, refer to Philips specs.: SNW-EQ-608, SNW-FQ-302A and SNW-FQ-302B.

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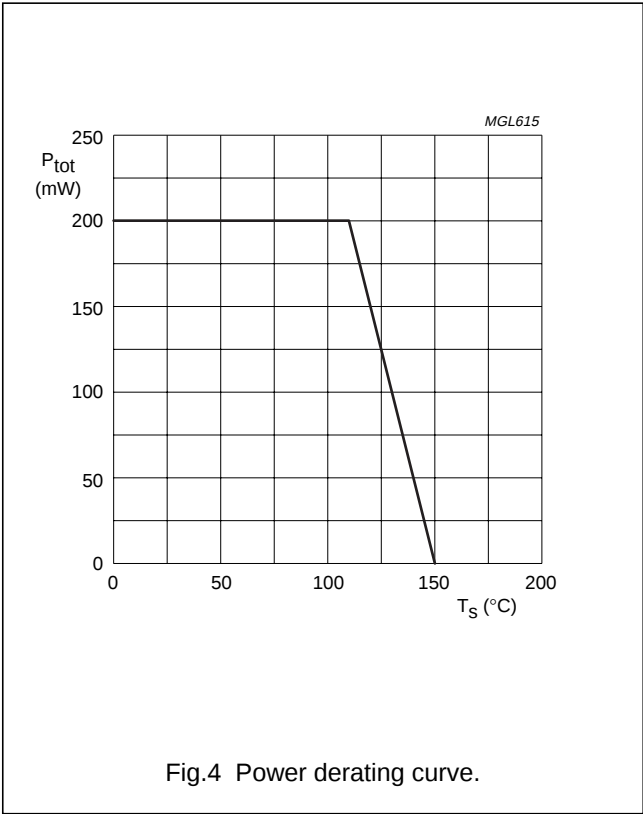
LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{DS}	drain-source voltage		–	7	V
I _D	drain current		–	30	mA
I _{G1}	gate 1 current		–	±10	mA
I _{G2}	gate 2 current		–	±10	mA
P _{tot}	total power dissipation	T _s ≤ 110 °C; note 1; see Fig.4	–	200	mW
T _{stg}	storage temperature		–65	+150	°C
T _j	operating junction temperature		–	150	°C

Note

1. T_s is the temperature of the soldering point of the source lead.



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THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-s}$	thermal resistance from junction to soldering point	note 1	200	K/W

Note

1. Soldering point of the source lead.

STATIC CHARACTERISTICS

$T_j = 25\text{ °C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{(BR)G1-SS}$	gate 1-source breakdown voltage	$V_{G2-S} = V_{DS} = 0$; $I_{G1-S} = 10\text{ mA}$	6	15	V
$V_{(BR)G2-SS}$	gate 2-source breakdown voltage	$V_{G1-S} = V_{DS} = 0$; $I_{G2-S} = 10\text{ mA}$	6	15	V
$V_{(F)S-G1}$	forward source-gate 1 voltage	$V_{G2-S} = V_{DS} = 0$; $I_{S-G1} = 10\text{ mA}$	0.5	1.5	V
$V_{(F)S-G2}$	forward source-gate 2 voltage	$V_{G1-S} = V_{DS} = 0$; $I_{S-G2} = 10\text{ mA}$	0.5	1.5	V
$V_{G1-S(th)}$	gate 1-source threshold voltage	$V_{G2-S} = 4\text{ V}$; $V_{DS} = 5\text{ V}$; $I_D = 20\text{ }\mu\text{A}$	0.3	1	V
$V_{G2-S(th)}$	gate 2-source threshold voltage	$V_{G1-S} = V_{DS} = 5\text{ V}$; $I_D = 20\text{ }\mu\text{A}$	0.3	1.2	V
I_{DSX}	drain-source current	$V_{G2-S} = 4\text{ V}$; $V_{DS} = 5\text{ V}$; $R_{G1} = 120\text{ k}\Omega$; note 1	8	13	mA
I_{G1-SS}	gate 1 cut-off current	$V_{G2-S} = V_{DS} = 0$; $V_{G1-S} = 5\text{ V}$	–	50	nA
I_{G2-SS}	gate 2 cut-off current	$V_{G1-S} = V_{DS} = 0$; $V_{G2-S} = 5\text{ V}$	–	50	nA

Note

1. R_{G1} connects gate 1 to $V_{GG} = 5\text{ V}$; see Fig.21.

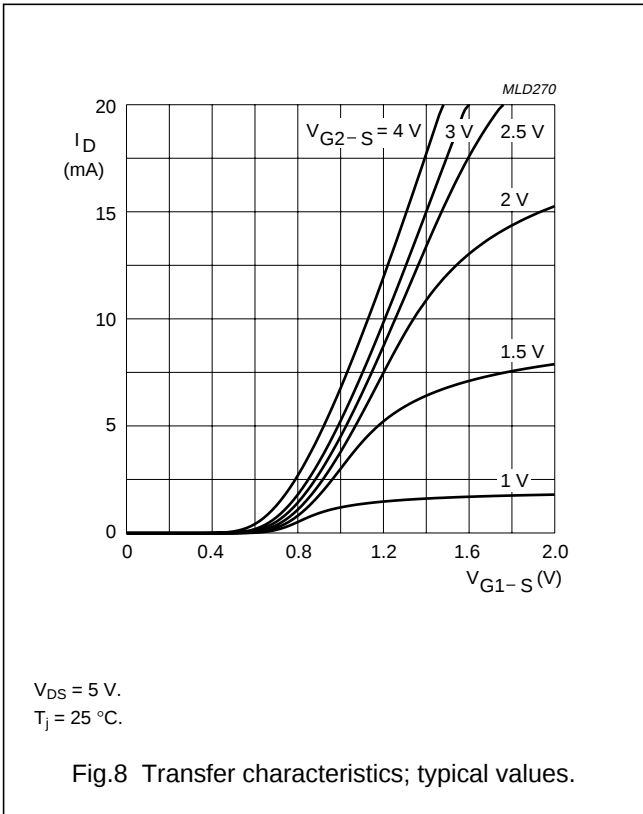
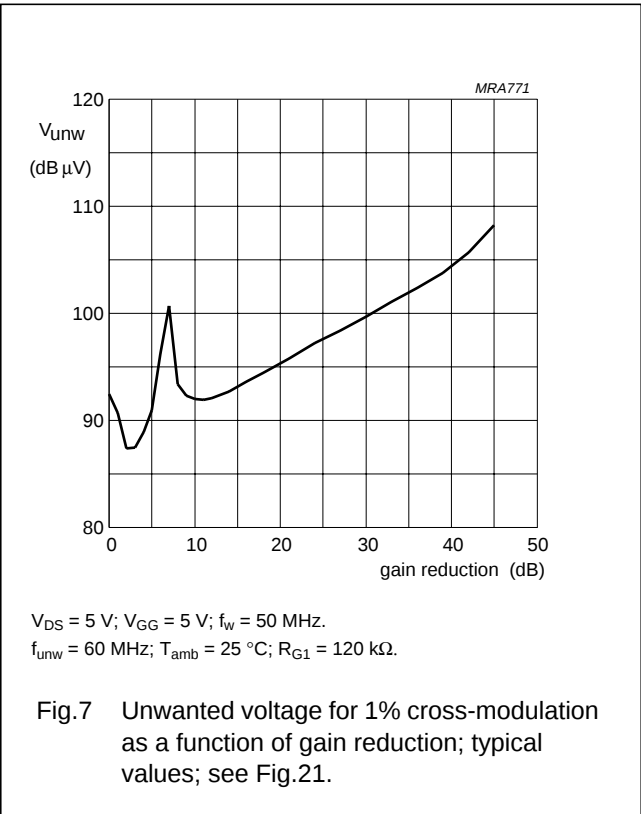
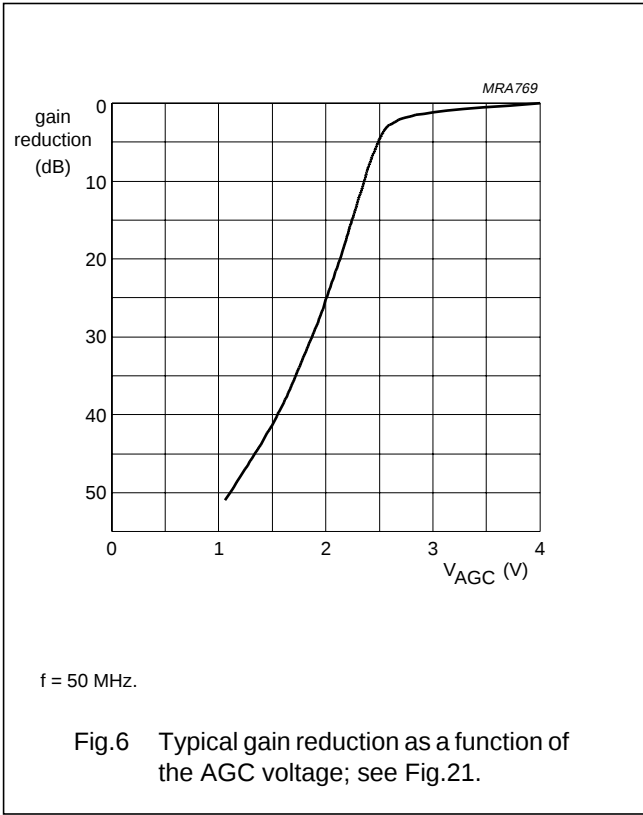
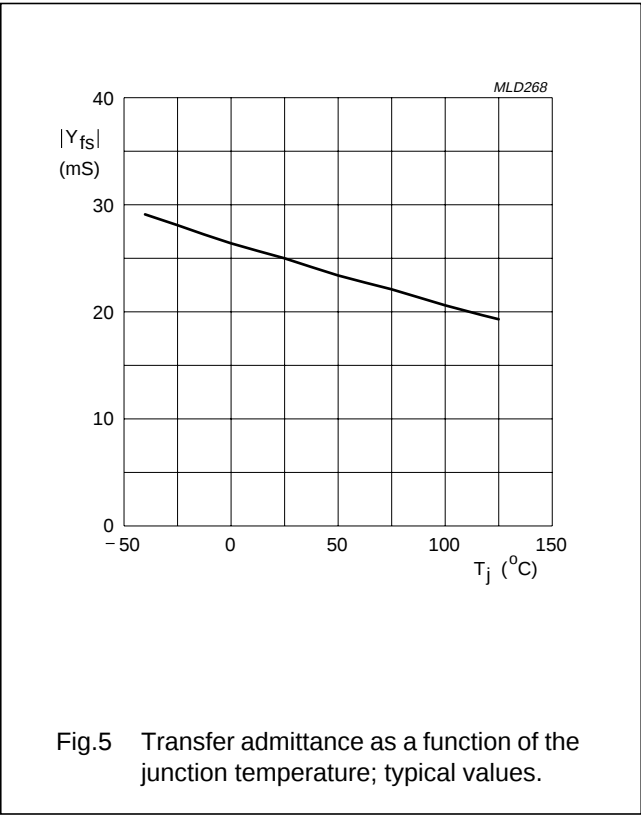
DYNAMIC CHARACTERISTICS

Common source; $T_{amb} = 25\text{ °C}$; $V_{DS} = 5\text{ V}$; $V_{G2-S} = 4\text{ V}$; $I_D = 10\text{ mA}$; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$ y_{fs} $	forward transfer admittance	pulsed; $T_j = 25\text{ °C}$	22	25	30	mS
C_{ig1-s}	input capacitance at gate 1	$f = 1\text{ MHz}$	–	2.2	2.6	pF
C_{ig2-s}	input capacitance at gate 2	$f = 1\text{ MHz}$	1	1.5	2	pF
C_{os}	drain-source capacitance	$f = 1\text{ MHz}$	1	1.4	1.7	pF
C_{rs}	reverse transfer capacitance	$f = 1\text{ MHz}$	–	25	35	fF
F	noise figure	$f = 200\text{ MHz}$; $G_S = 2\text{ mS}$; $B_S = B_{Sopt}$	–	1	1.5	dB
		$f = 800\text{ MHz}$; $G_S = G_{Sopt}$; $B_S = B_{Sopt}$	–	2	2.8	dB

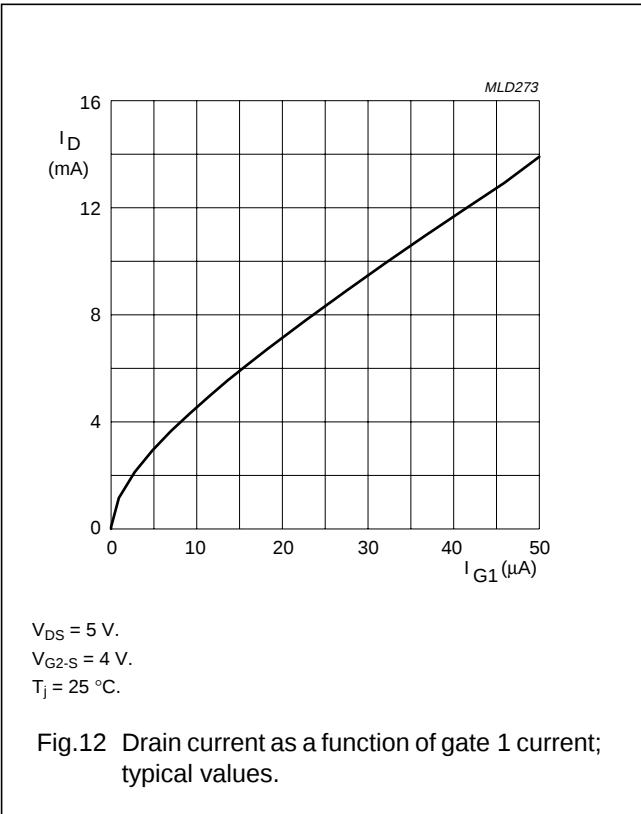
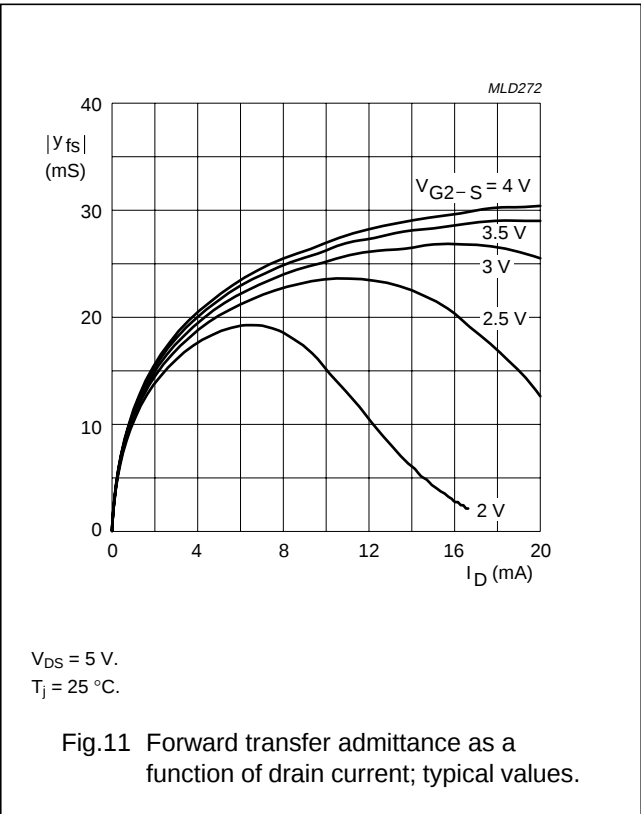
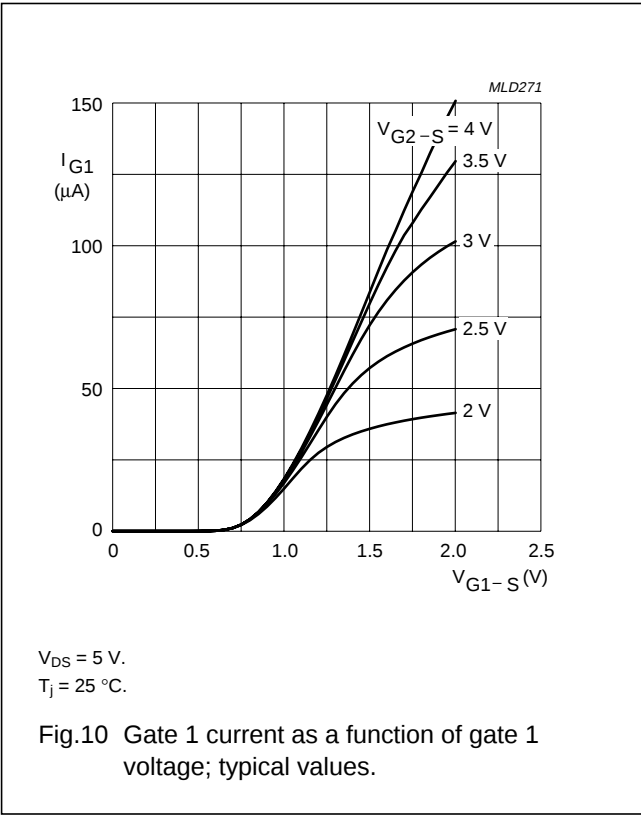
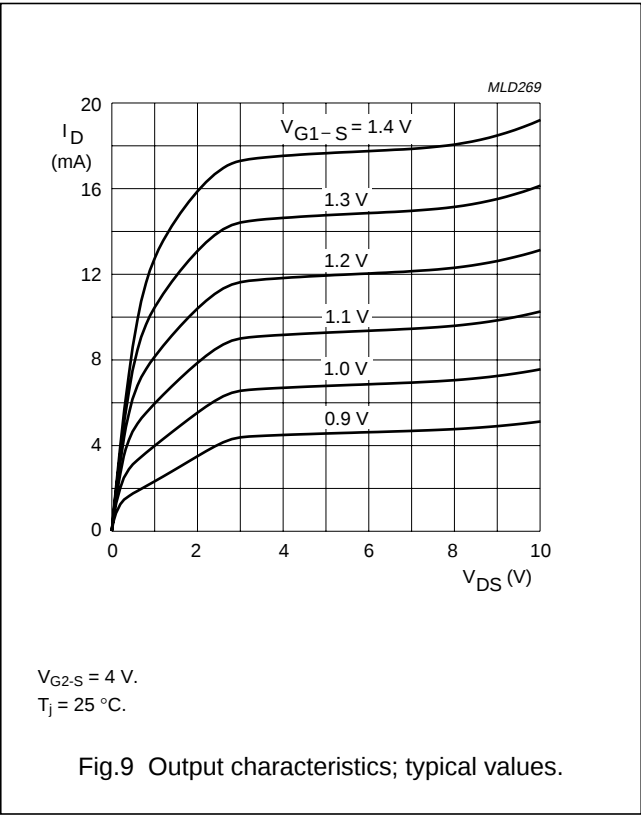
N-channel dual gate MOS-FETs

BF904A; BF904AR; BF904AWR



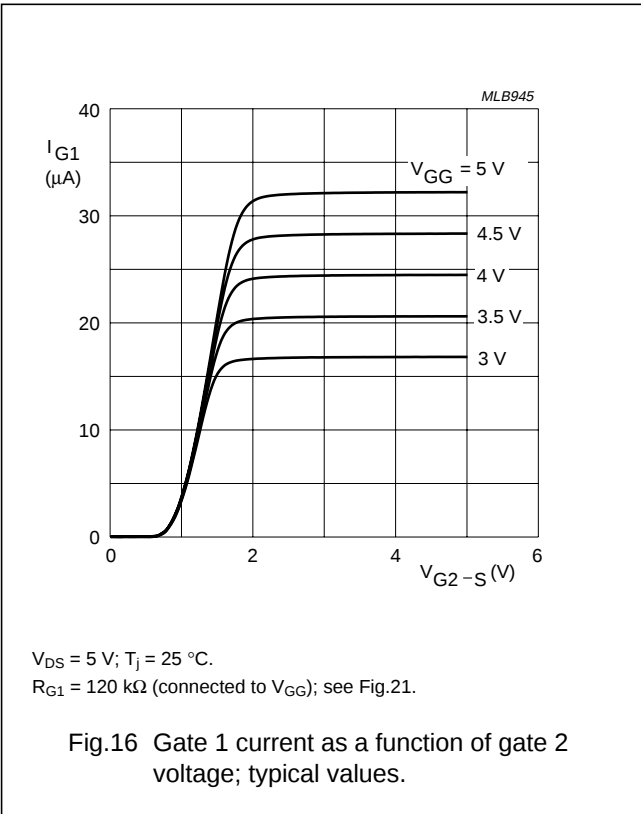
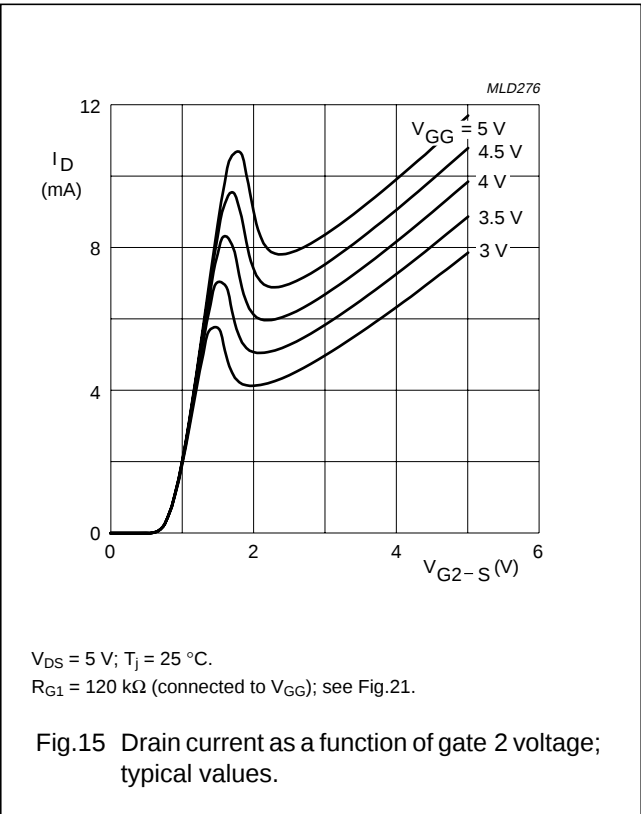
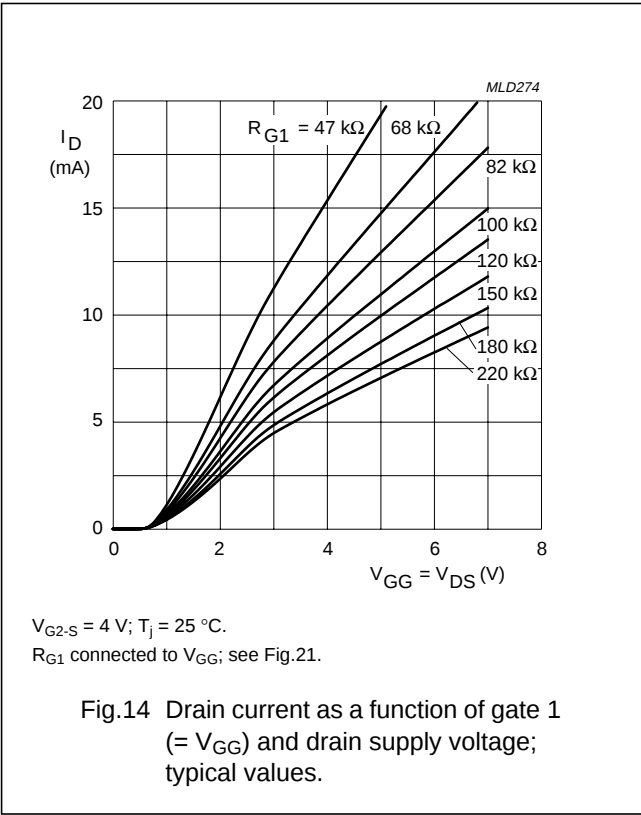
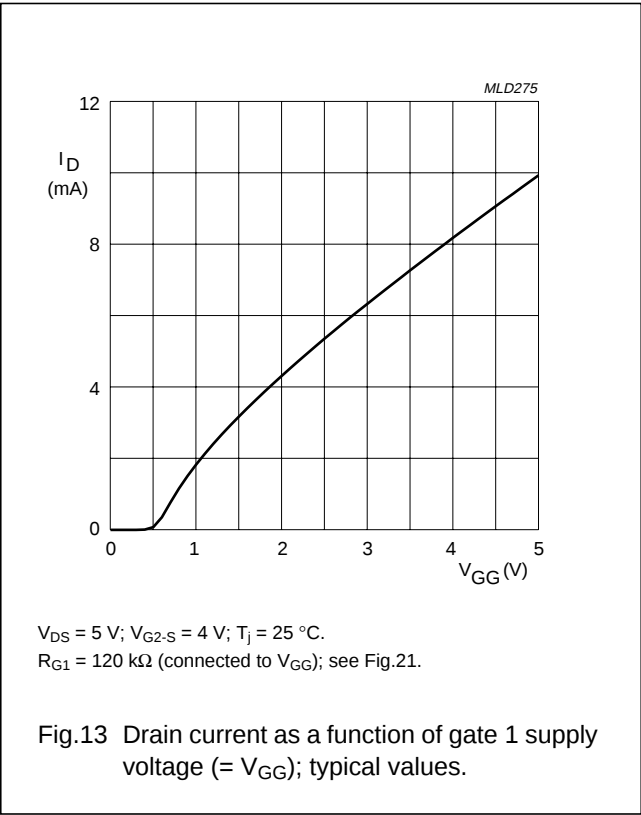
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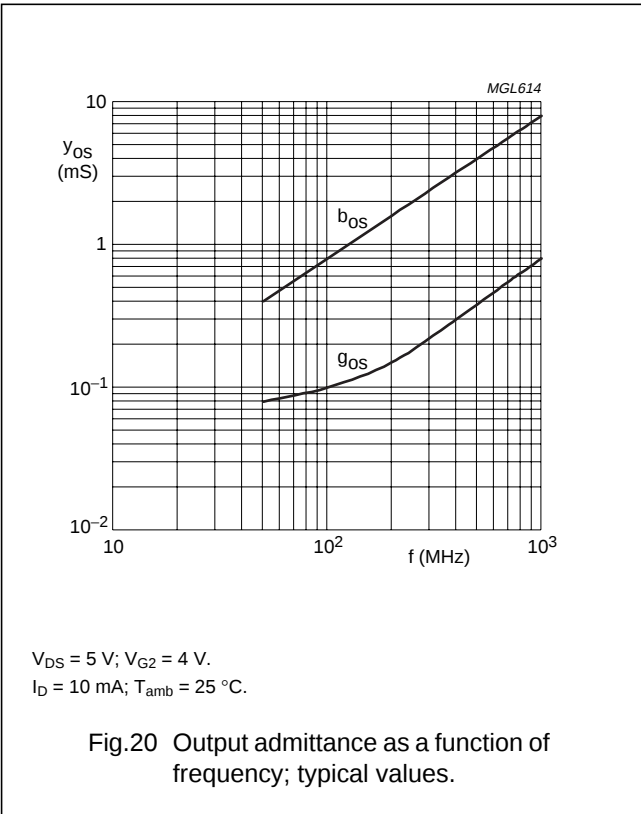
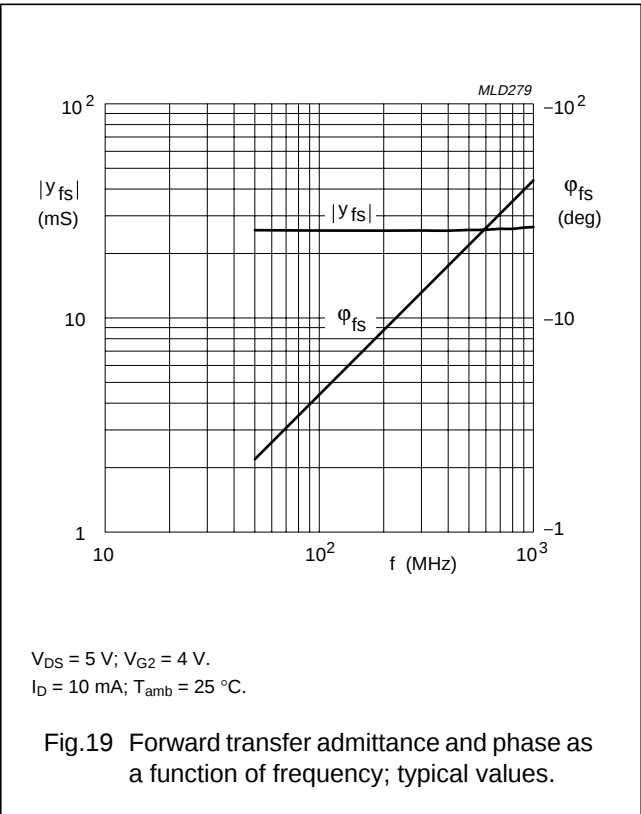
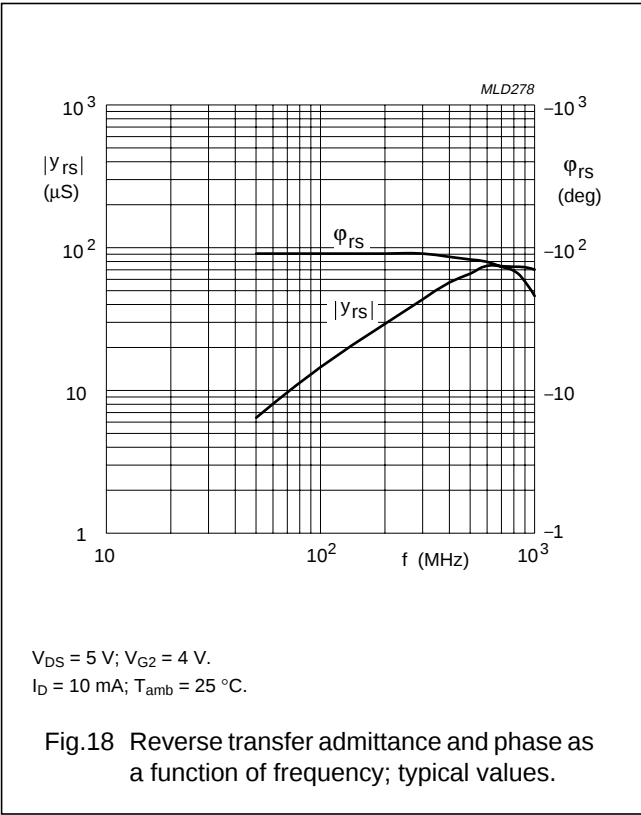
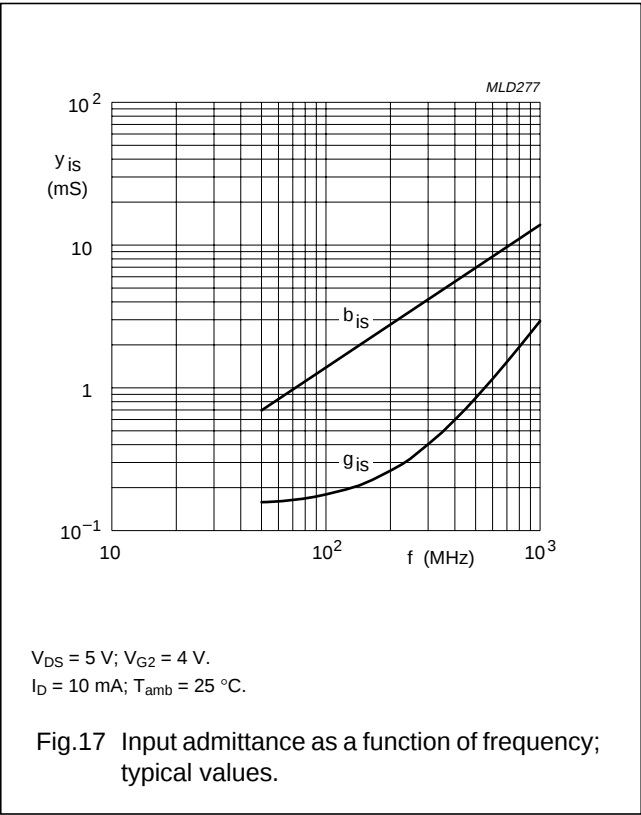
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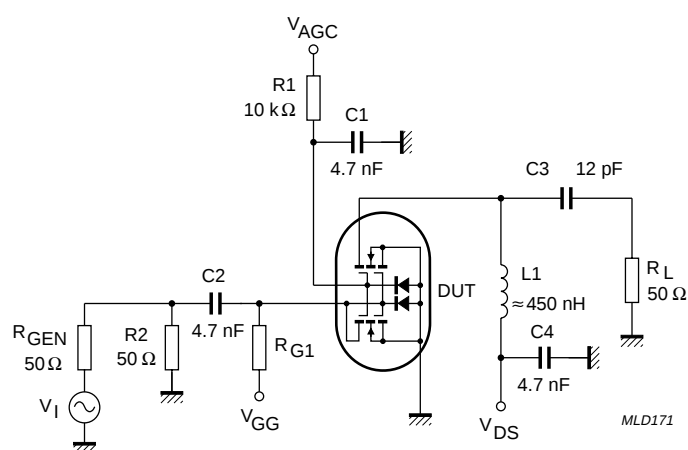


Fig.21 Cross-modulation test set-up.

N-channel dual gate MOS-FETs

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Table 1 Scattering parameters: $V_{DS} = 5\text{ V}$; $V_{G2-S} = 4\text{ V}$; $I_D = 10\text{ mA}$; $T_{amb} = 25\text{ °C}$

f (MHz)	S ₁₁		S ₂₁		S ₁₂		S ₂₂	
	MAGNITUDE (ratio)	ANGLE (deg)	MAGNITUDE (ratio)	ANGLE (deg)	MAGNITUDE (ratio)	ANGLE (deg)	MAGNITUDE (ratio)	ANGLE (deg)
40	0.989	-3.2	2.52	175.9	0.001	87.9	0.989	-1.7
100	0.987	-7.9	2.52	169.4	0.001	86.1	0.988	-4.3
200	0.976	-15.7	2.47	159.2	0.003	81.4	0.984	-8.6
300	0.972	-23.3	2.43	150.5	0.004	80.5	0.985	-12.7
400	0.947	-30.6	2.36	139.6	0.005	76.9	0.975	-16.9
500	0.925	-37.6	2.26	130.3	0.005	75.6	0.968	-20.8
600	0.905	-44.4	2.19	121.1	0.005	75.5	0.961	-24.7
700	0.883	-50.9	2.10	112.3	0.006	78.0	0.954	-28.4
800	0.861	-57.0	2.01	103.6	0.006	85.3	0.946	-32.0
900	0.841	-63.0	1.93	95.5	0.006	90.7	0.934	-35.6
1000	0.822	-68.4	1.85	87.8	0.006	102.6	0.931	-39.3
1200	0.787	-78.9	1.71	72.3	0.007	127.1	0.923	-46.7
1400	0.752	-88.1	1.59	57.3	0.011	143.7	0.926	-54.2
1600	0.723	-97.3	1.47	40.1	0.019	150.0	0.935	-62.2
1800	0.685	-106.3	1.36	25.0	0.021	149.4	0.931	-69.3
2000	0.665	-114.0	1.31	7.7	0.026	151.5	0.930	-77.7
2200	0.659	-119.8	1.30	-14.0	0.035	158.2	0.944	-89.1
2400	0.670	-124.2	1.26	-42.2	0.050	163.4	0.941	-103.5
2600	0.700	-129.3	1.10	-78.2	0.076	162.2	0.849	-119.7
2800	0.729	-138.7	0.82	-120.8	0.106	150.5	0.642	-130.9
3000	0.726	-150.1	0.52	-162.8	0.128	137.4	0.480	-130.6

Table 2 Noise data: $V_{DS} = 5\text{ V}$; $V_{G2-S} = 4\text{ V}$; $I_D = 10\text{ mA}$; $T_{amb} = 25\text{ °C}$

f (MHz)	F _{min} (dB)	Γ _{opt}		R _n (Ω)
		(ratio)	(deg)	
800	2.0	0.686	49.6	50.4

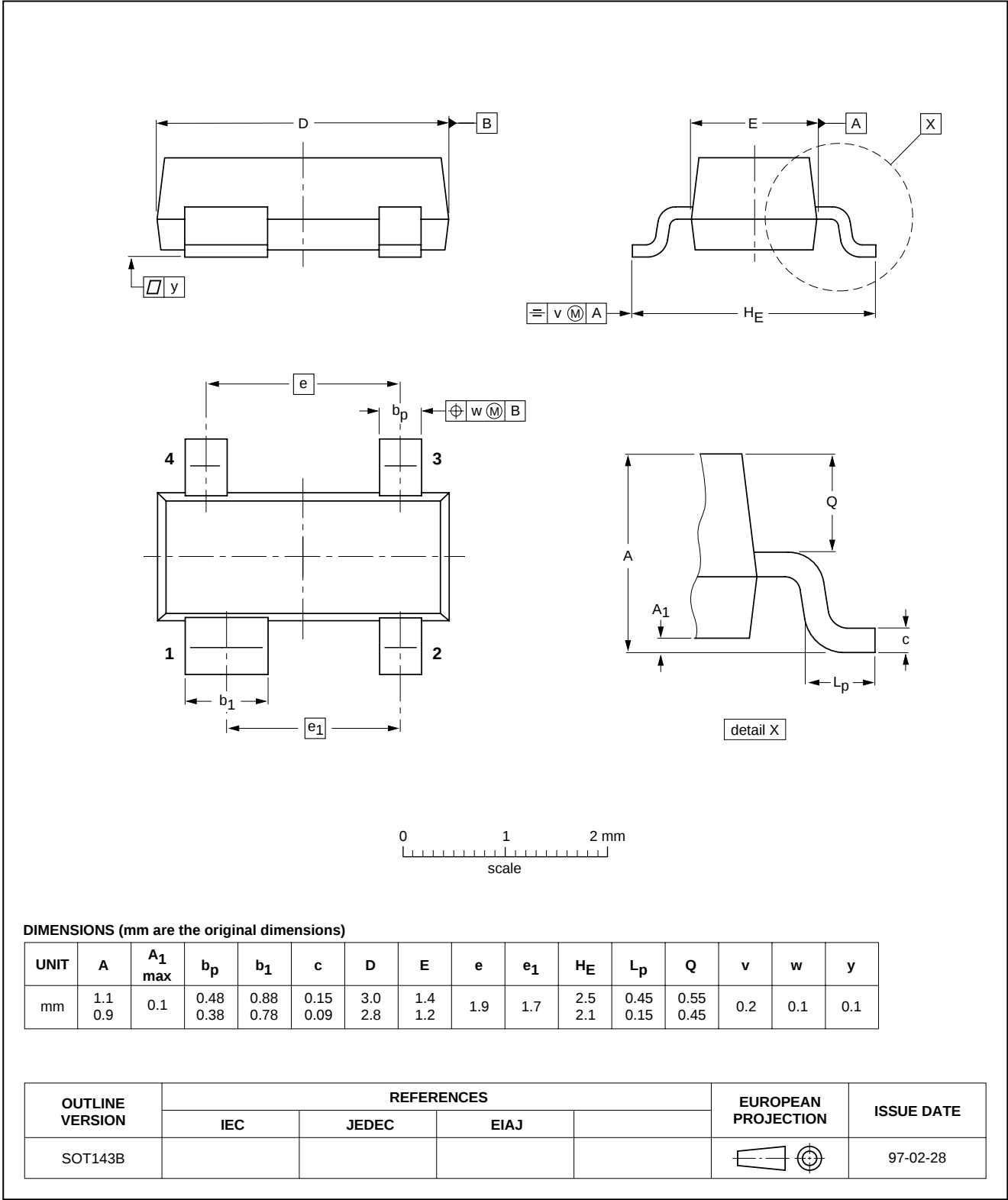
N-channel dual gate MOS-FETs

BF904A; BF904AR; BF904AWR

PACKAGE OUTLINES

Plastic surface mounted package; 4 leads

SOT143B

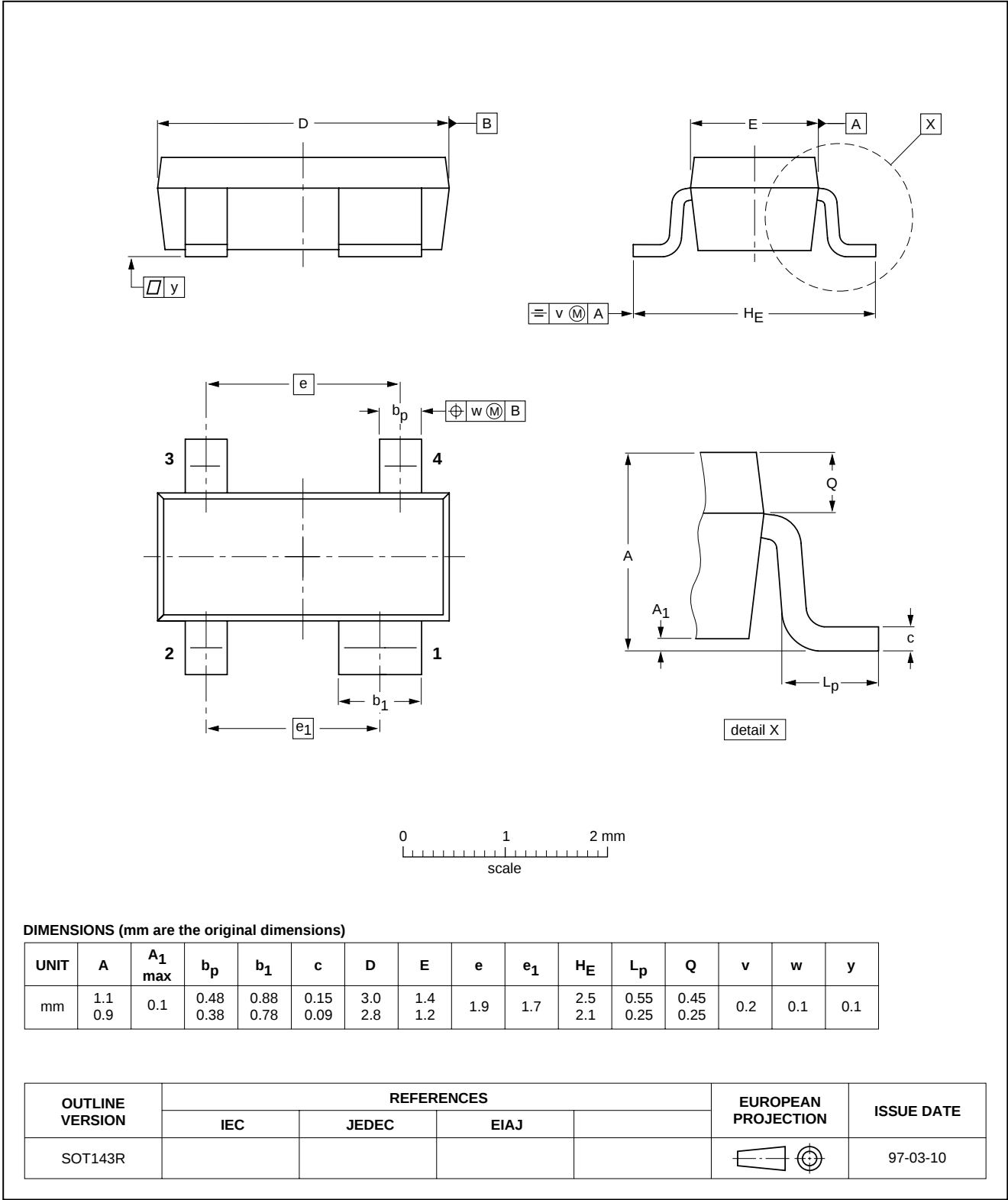


N-channel dual gate MOS-FETs

BF904A; BF904AR; BF904AWR

Plastic surface mounted package; reverse pinning; 4 leads

SOT143R

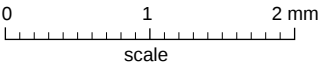
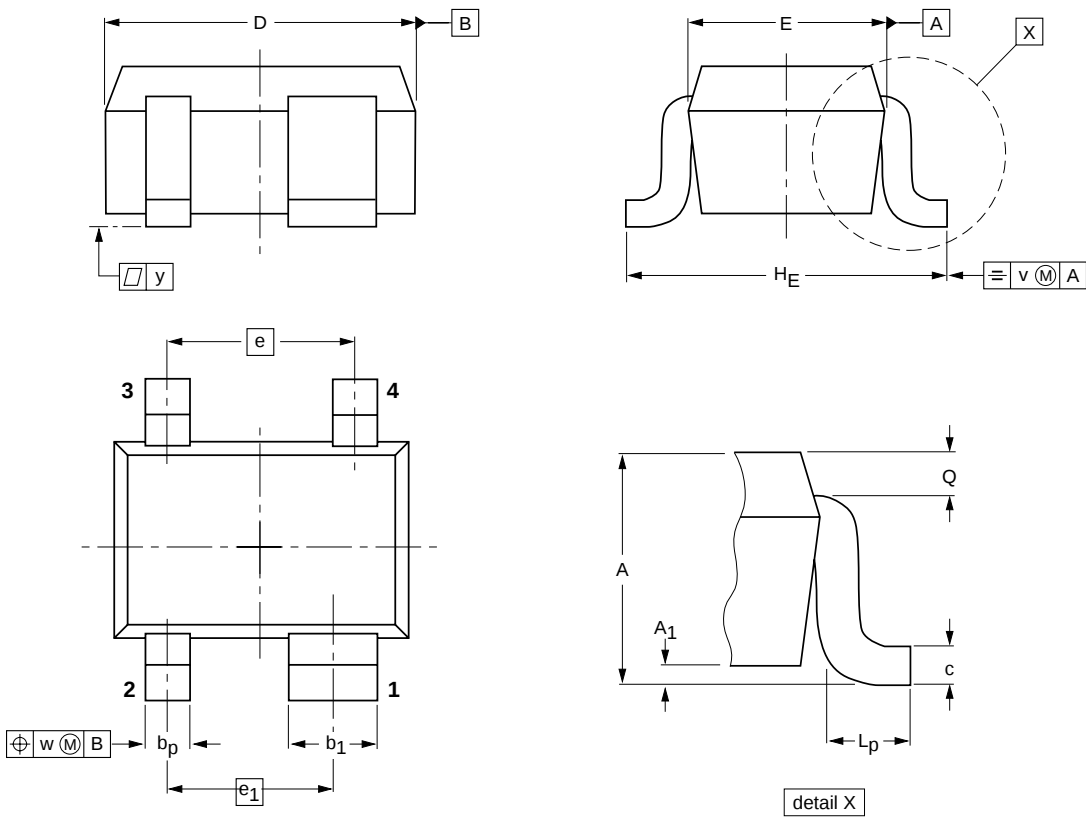


N-channel dual gate MOS-FETs

BF904A; BF904AR; BF904AWR

Plastic surface mounted package; reverse pinning; 4 leads

SOT343R



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	b _p	b ₁	c	D	E	e	e ₁	H _E	L _p	Q	v	w	y
mm	1.1 0.8	0.1	0.4 0.3	0.7 0.5	0.25 0.10	2.2 1.8	1.35 1.15	1.3	1.15	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT343R						97-05-21

N-channel dual gate MOS-FETs

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DEFINITIONS

Data Sheet Status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

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Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



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